United States Patent [19]

Wallgren

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[45] **Date of Patent: ** Feb. 24, 1987**

[54] **FRAME OF DUAL IN LINE PACKAGE PADS UTILIZED TO REPLACE DAMAGED PADS ON PRINTED CIRCUIT BOARDS**

[75] Inventor: **Linus E. Wallgren**, Rockville, Md.

[73] Assignee: **Pace, Incorporated**, Laurel, Md.

[**] Term: **14 Years**

[21] Appl. No.: **582,028**

[22] Filed: **Feb. 21, 1984**

[52] **U.S. Cl.** **D13/99**

[58] **Field of Search** .... D13/24, 25, 27-31; D9/337, 341, 456, 424; 339/276 SF, 17 C, 147 R; 206/328, 330, 820; 29/163.5 R, 825, 883, 884

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Primary Examiner—Susan J. Lucas

Attorney, Agent, or Firm—Gerald J. Ferguson, Jr.; Michael P. Hoffman; Ronni S. Malamud

[57] **CLAIM**

The ornamental design for a frame of dual in line package pads utilized to replace damaged pads on printed circuit boards, as shown and described.

DESCRIPTION

The sole FIGURE is a top plan view of the frame of dual in line package pads utilized to replace damaged pads on printed circuit boards showing my new design. The frame is flat with no substantial thickness and the bottom surface is identical to the top.